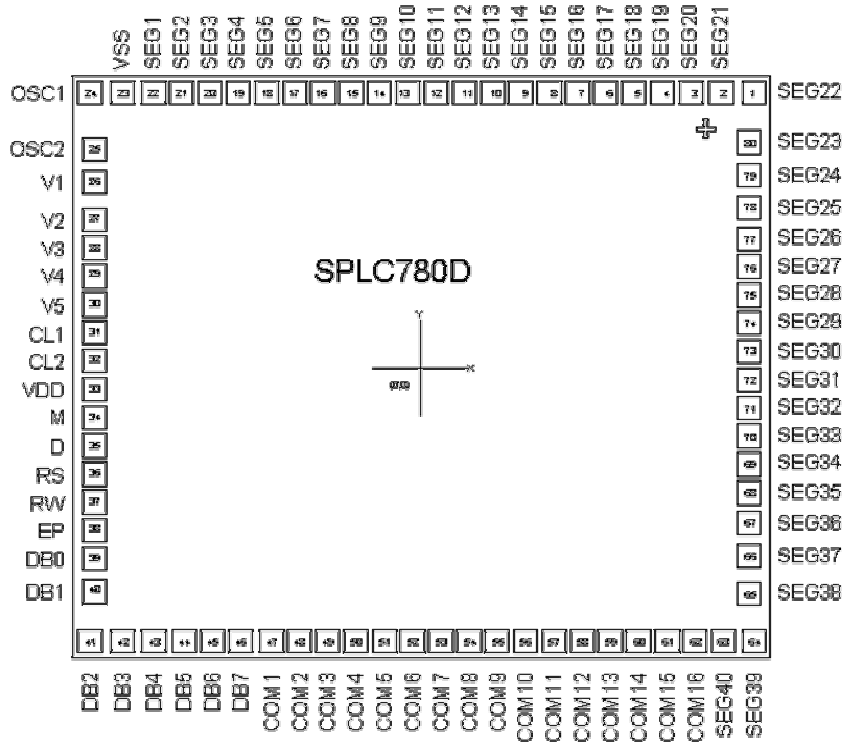


SPLC780D

- 16COM/40SEG Controller/Driver

1. PACKAGE/PAD LOCATIONS

1.1. PAD Assignment



Chip Size: 2860 μ m x 2450 μ m

PAD Size: 90 μ m x 90 μ m

This IC substrate should be connected to VDD

Note1: Chip size included scribe line.

Note2: To ensure that the IC functions properly, please bond all of VDD and VSS pins.

Note3: The 0.1 μ F capacitor between VDD and VSS should be placed to IC as close as possible.

1.2. Ordering Information

Product Number	Package Type
SPLC780D-NnnV-C	Chip form
SPLC780D-NnnV-PQ05	Package form - QFP 80L

Note1: Code number is assigned for customer.

Note2: Code number (N = A - Z or 0 - 9, nn = 00 - 99); version (V = A - Z).

1.3. PAD Locations

PAD No.	PAD Name	X	Y	PAD No.	PAD Name	X	Y
1	SEG22	1295.0	1058.5	41	DB2	-1295.0	-1058.5
2	SEG21	1175.0	1058.5	42	DB3	-1175.0	-1058.5
3	SEG20	1055.0	1058.5	43	DB4	-1055.0	-1058.5
4	SEG19	940.0	1058.5	44	DB5	-940.0	-1058.5
5	SEG18	825.0	1058.5	45	DB6	-825.0	-1058.5
6	SEG17	715.0	1058.5	46	DB7	-715.0	-1058.5
7	SEG16	605.0	1058.5	47	COM1	-605.0	-1058.5
8	SEG15	495.0	1058.5	48	COM2	-495.0	-1058.5
9	SEG14	385.0	1058.5	49	COM3	-385.0	-1058.5
10	SEG13	275.0	1058.5	50	COM4	-275.0	-1058.5
11	SEG12	165.0	1058.5	51	COM5	-165.0	-1058.5
12	SEG11	55.0	1058.5	52	COM6	-55.0	-1058.5
13	SEG10	-55.0	1058.5	53	COM7	55.0	-1058.5
14	SEG9	-165.0	1058.5	54	COM8	165.0	-1058.5
15	SEG8	-275.0	1058.5	55	COM9	275.0	-1058.5
16	SEG7	-385.0	1058.5	56	COM10	385.0	-1058.5
17	SEG6	-495.0	1058.5	57	COM11	495.0	-1058.5
18	SEG5	-605.0	1058.5	58	COM12	605.0	-1058.5
19	SEG4	-715.0	1058.5	59	COM13	715.0	-1058.5
20	SEG3	-825.0	1058.5	60	COM14	825.0	-1058.5
21	SEG2	-940.0	1058.5	61	COM15	940.0	-1058.5
22	SEG1	-1055.0	1058.5	62	COM16	1055.0	-1058.5
23	VSS	-1175.0	1058.5	63	SEG40	1175.0	-1058.5
24	OSC1	-1295.0	1058.5	64	SEG39	1295.0	-1058.5
25	OSC2	-1268.0	853.7	65	SEG38	1259.8	-856.3
26	V1	-1259.8	733.7	66	SEG37	1259.8	-736.3
27	V2	-1259.8	613.7	67	SEG36	1259.8	-616.3
28	V3	-1259.8	498.7	68	SEG35	1259.8	-501.3
29	V4	-1259.8	383.7	69	SEG34	1259.8	-386.3
30	V5	-1259.8	273.7	70	SEG33	1259.8	-276.3
31	CL1	-1259.8	163.7	71	SEG32	1259.8	-166.3
32	CL2	-1259.8	53.7	72	SEG31	1259.8	-56.3
33	VDD	-1259.8	-56.3	73	SEG30	1259.8	53.7
34	M	-1259.8	-166.3	74	SEG29	1259.8	163.7
35	D	-1259.8	-276.3	75	SEG28	1259.8	273.7
36	RS	-1259.8	-386.3	76	SEG27	1259.8	383.7
37	R/W	-1259.8	-501.3	77	SEG26	1259.8	498.7
38	E	-1259.8	-616.3	78	SEG25	1259.8	613.7
39	DB0	-1259.8	-736.3	79	SEG24	1259.8	733.7
40	DB1	-1259.8	-856.3	80	SEG23	1259.8	853.7

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3. REVISION HISTORY

Date	Revision #	Description	Page
AUG. 07, 2003	1.0	Original	4

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